

YES-PB12 High Vacuum Oven

For Copper Anneal Essential for MEMS and Wafer-level Packaging

Specifications

| Class 10 Chamber Cleanliness | Hardware | | | |
|--|--|--------------|---|--------------|
| Operation Temperature Ambient to 450 °C Nitrogen Consumption 15-25 liters/min. Interior Chamber Dimensions 53.34 cm barrel (ID) x 76.96 cm (D) (21" x 30.3") Chamber Process Area 37.59 cm (W) x 56.64 cm (D) x 36.07 cm (H) (14.8" x 22.3" x 14.2") Overall System Dimensions 85.85 cm (W) x 203 cm (D) x 95 cm (H) (33.8" x 80.0" x 37.4") 33.6L stainless steel Process Gas Inputs 1 standard, up to 3 optional Mass Flow Controllers Optional – up to 3 for gas mixing Laminar Flow Filter 100 micron Mott™ plate filter Cleanliness Particle reduction in most applications Software Number of Recipes Number of Steps for Each Recipe 16 program steps Range of Segment Time 0-99 hours Resolution of Timer Setting 1 minute Performance 0xygen Concentration Maximum Heat-Up Rate (150°C-450°C) 6.5 °C/min. (at low end of range: changes ~ 1°C/100°C increment) Maximum Rool-Down Rate (450°C - 150°C) 3.5 °C/min. (at high end of range: changes ~ 1°C/100°C increment) Maximum Process Pressure Range 50-400Torr High Vacuum Base Pressure 15.25 liters/min <t< td=""><td colspan="2">Clean Room Compatibility</td><td colspan="2">Class 10</td></t<> | Clean Room Compatibility | | Class 10 | |
| Nitrogen Consumption | Chamber Cleanliness | | Class 1 | |
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| 125 mm wafers 10 cassettes | 100 mm wafers | 10 cassettes | 300 mm wafers | 2 cassettes |
| | 125 mm wafers | 10 cassettes | | |

Tool temperature performance is a combination of temperature control accuracy and temperature uniformity. Accuracy is the deviation of the average product temperature from the set point. Uniformity is the deviation between the maximum and minimum product temperatures and is not related to the set point. Accuracy is calculated as set point — average temperature. Uniformity is calculated as (max-min)/(max+min). YES-PB series tools have dwell accuracy of +/-1.5°C after stabilization. YES-450PB12-2P-CP has a uniformity of +/-5°C. After stabilizing at dwell, all product temperatures should be within 10°C or 14°C of each other (depending on the tool) and within 7°C or 8.5°C of set point (depending on the tool).



Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at www.yieldengineering.com.

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